

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (canceled).
2. (currently amended): A circuit board unit comprising:
 - a first substrate including, on a surface thereof, a first group of electrode terminals arranged in a matrix;
 - a second substrate including, on a surface thereof, a second group of electrode terminals arranged in a matrix in alignment with said first group of electrode terminals;
 - an anisotropic electrical conductor sandwiched between said first and second substrates, wherein said anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of gold-plated particles, silver-plated particles, and copper-plated particles; and
 - a pressurizer pressurizing said first substrate, said anisotropic electrical conductor, and said second substrate wherein said first substrate, said anisotropic electrical conductor, and said second substrate are caused to electrically connect to each other,
 - wherein said pressurizer is composed of a material having a spring characteristic.

3. (original) The circuit board unit as set forth in claim 2, wherein said pressurizer includes a first plane which makes contact with said first substrate, a second plane which makes contact with said second substrate, and a third plane which keeps said first and second planes in parallel with each other.

4.-10. (canceled).

11. (currently amended): A method of connecting a first substrate and a second substrate to each other, the method comprising:

arranging an anisotropic electrical conductor between said first and second substrates, wherein said anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of gold-plated particles, silver-plated particles, and copper-plated particles,

wherein said first substrate includes, on a surface thereof, a first group of electrode terminals arranged in a matrix, and said second substrate includes, on a surface thereof, a second group of electrode terminals arranged in a matrix in alignment with said first group of electrode terminals; and

attaching a pressurizer to said first substrate, said second substrate, and said anisotropic electrical conductor to pressurize said first substrate, said second substrate, and said anisotropic electrical conductor in a thickness-wise direction thereof to electrically connect to each other,

wherein said pressurizer is composed of a material having a spring characteristic.

12. (previously presented): The circuit board unit as set forth in claim 2, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate, and

a recess caused by said via-hole is absorbed into said anisotropic electrical conductor due to elasticity thereof when said first substrate, said anisotropic electrical conductor, and said second substrate are pressurized.

13. (previously presented): The circuit board unit as set forth in claim 2, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

said each of electrode terminals has a planar area in which said via-hole is not formed,
and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said planar area.

14. (previously presented): The circuit board unit as set forth in claim 2, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

an exposed surface of said each of electrode terminals defines a planar surface, and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said exposed surface.

15. (canceled).

16. (previously presented): The circuit board unit as set forth in claim 2, wherein each of said first and second substrates is comprised of one of a multi-layered flexible circuit board, a multi-layered rigid printing circuit board, a double-sided flexible circuit board, and a double-sided rigid printing circuit board.

17. (previously presented): The circuit board as set forth in claim 2, further comprising an adhesive layer formed on surfaces of said anisotropic electrical conductor.

18. (currently amended): A circuit board unit comprising:

a first substrate including, on a surface thereof, a first group of electrode terminal arranged in a matrix;

a second substrate including, on a surface thereof, a second group of electrode terminals arranged in a matrix in alignment with said first group electrode terminals;

an anisotropic electrical conductor sandwiched between said first and second substrates, wherein said anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of gold-plated particles, silver-plated particles, and copper-plated particles; and

a pressurizer pressurizing said first substrate, said anisotropic electrical conductor, and said second substrate such that they make close contact with one another,

said pressurizer including a first plane which makes contact with said first substrate, a second plane which makes contact with said second substrate, and a third plane which keeps said first and second planes in parallel with each other,

said pressurizer being composed of a material having a spring characteristic,

wherein said first substrate, said anisotropic electrical conductor, and said second substrate are caused to make close contact with one another in a pressurized condition to electrically connect said first group of electrode terminals and said second group of electrode terminals to each other.

19. (previously presented): The circuit board unit as set forth in claim 18, wherein each of electrode terminals in said first and second groups of electrode terminals is formed with at least one via-hole,

at least one wire extends from said first and second groups of electrode terminals through said via-hole and inner layers or a lower surface of said first substrate,

an exposed surface of said each of electrode terminals defines a planar surface, and

said each of electrode terminals makes contact with said anisotropic electrical conductor through said exposed surface.

20. (canceled).

21. (previously presented): The circuit board unit as set forth in claim 18, wherein each of said first and second substrates is comprised of one of a multi-layered flexible circuit board, a multi-layered rigid printing circuit board, a double-sided flexible circuit board, and a double-sided rigid printing circuit board.

22. (previously presented): The circuit board unit as set forth in claim 18, further comprising an adhesive layer formed on surfaces of said anisotropic electrical conductor.

23. (currently amended): A method of connecting a first substrate including, on a surface thereof, a first group of electrode terminals, and a second substrate including, on a surface

thereof, a second group of electrode terminals arranged in alignment with said first group of electrode terminals, to each other, comprising:

arranging an anisotropic electrical conductor between said first and second substrates, wherein said anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of gold-plated particles, silver-plated particles, and copper-plated particles; and

pressurizing said first substrate, said second substrate, and said anisotropic electrical conductor in a thickness-wise direction thereof through the use of a pressurizer to electrically connect said first group of electrode terminals and said second group of electrode terminals to each other,

said pressurizer pressurizing said first substrate, said anisotropic electrical conductor, and said second substrate such that they make close contact with one another,

said pressurizer including a first plane which makes contact with said first substrate, a second plane which makes contact with said second substrate, and a third plane which keeps said first and second planes in parallel with each other,

said pressurizer being composed of a material having a spring characteristic.